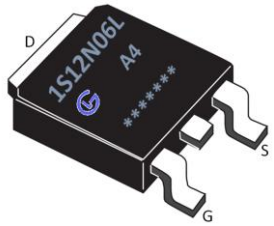
GL Silicon N-Channel Power MOSFET

V_{DSS}	60	V
I_D	12	A
P_D	35	W
$R_{DS(ON)typ}$	58	mΩ

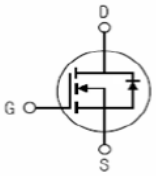
General Description

The GL1S12N06LA4 uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications. The package form is TO-252, which accords with the RoHS standard.

TO-252



Inner Equivalent Principium Chart



Features

- Fast Switching
- Low Gate Charge and Rdson
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

Absolute (Tc= 25℃ unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-to-Source Voltage	60	V
I_D	Continuous Drain Current	12	A
	Continuous Drain Current T_C = 100 °C	8.5	A
I_{DM}	Pulsed Drain Current	48	A
V_{GS}	Gate-to-Source Voltage	±20	V
E_{AS} [a2]	Single Pulse Avalanche Energy	30	mJ
E_{AR} [a1]	Avalanche Energy ,Repetitive	10	mJ
I_{AR} [a1]	Avalanche Current	6	A
dv/dt [a3]	Peak Diode Recovery dv/dt	5.0	V/ns
P_D	Power Dissipation	35	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	175, −55 to 175	℃
T_L	Maximum Temperature for Soldering	300	℃

Caution Stresses greater than those in the "Absolute Maximum Ratings" may cause permanent damage to the device

Electrical Characteristics (Tc=25℃ unless otherwise specified)

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V_{DSS}	Drain to Source Breakdown Voltage	V_{GS}=0V,I_D=250μA	60	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	I_D=250uA,Reference25℃	--	0.1	--	V/℃
I_{DSS}	Drain to Source Leakage Current	V_{DS}=60V,V_{GS}= 0V,T_a=25℃	--	--	1	μA
		V_{DS}=48V,V_{GS}=0V,T_a=125℃	--	--	250	
$I_{GSS(F)}$	Gate to Source Forward Leakage	V_{GS}=+20V	--	--	1	μA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	V_{GS}=-20V	--	--	-1	μA

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	V_{GS}=10V,I_D=6A	--	58	85	mΩ
$V_{GS(TH)}$	Gate Threshold Voltage	V_{DS}=V_{GS},I_D=250μA	1.0	1.4	2.5	V
Pulse width tp≤380μs,δ≤2%						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g_{fs}	Forward Transconductance	V_{DS}=15V,I_D=3A	2	--	--	S
C_{iss}	Input Capacitance	V_{GS}=0V,V_{DS}=30V f=1.0MHz	--	250	--	pF
C_{oss}	Output Capacitance		--	35	--	
C_{rss}	Reverse Transfer Capacitance		--	20	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	I_D=2A,V_{DD}=30V V_{GS}=10V,R_G=3.0Ω	--	6	--	ns
t_r	Rise Time		--	15	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	15	--	
t_f	Fall Time		--	10	--	
Q_g	Total Gate Charge	I_D=3A,V_{DD}=30V V_{GS}=10V	--	6.6	--	nC
Q_{gs}	Gate to Source Charge		--	1.2	--	
Q_{gd}	Gate to Drain (“Miller”)Charge		--	1.5	--	

Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I_S	Continuous Source Current (Body Diode)		--	--	12	A
I_{SM}	Maximum Pulsed Current (Body Diode)		--	--	48	A
V_{SD}	Diode Forward Voltage	I_S=12A,V_{GS}=0V	--	--	1.5	V
t_{rr}	Reverse Recovery Time	I_S=10A,T_j = 25°C	--	28	--	ns
Q_{rr}	Reverse Recovery Charge	dI_F/dt=100A/us,V_{GS}=0V	--	38	--	nC
Pulse width tp≤380μs,δ≤2%						

Thermal Characteristics

Symbol	Parameter	Typ.	Units
$R_{\theta Jc}$	Junction-to-Case	3.58	°C/W

[a1]: Repetitive rating; pulse width limited by maximum junction temperature
[a2]: EAS condition : Tj=25℃ ,VDD=30V,VG=10V,L=0.5mH,Rg=25Ω
[a3]: I_{SD} =10A,di/dt ≤100A/us,V_{DD}≤BV_{DS}, Start T_J=25℃

Test Circuit and Waveform

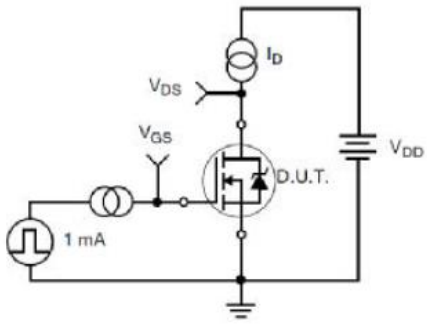


Figure 17. Gate Charge Test Circuit

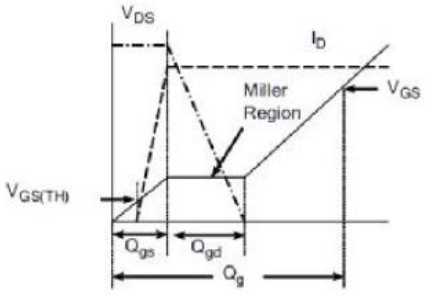


Figure 18. Gate Charge Waveform

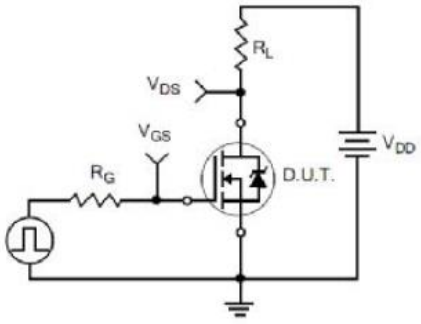


Figure 19. Resistive Switching Test Circuit

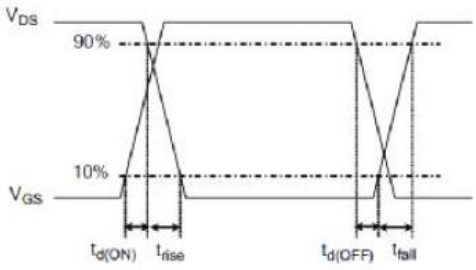


Figure 20. Resistive Switching Waveforms

Characteristics Curves

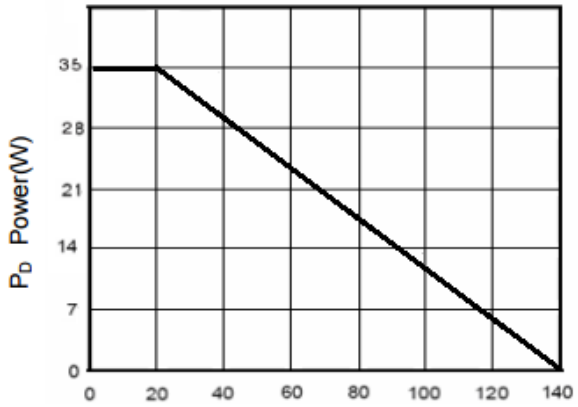


Figure 3 Power Dissipation

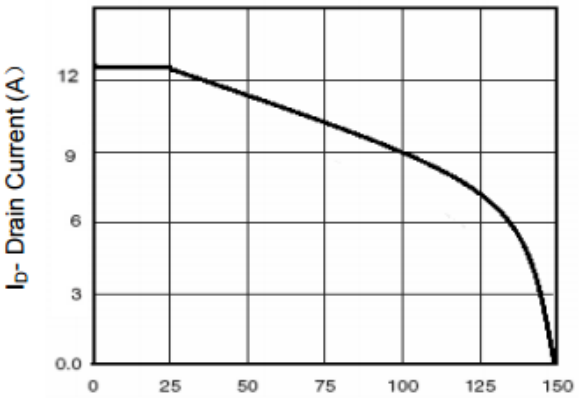


Figure 4 Drain Current

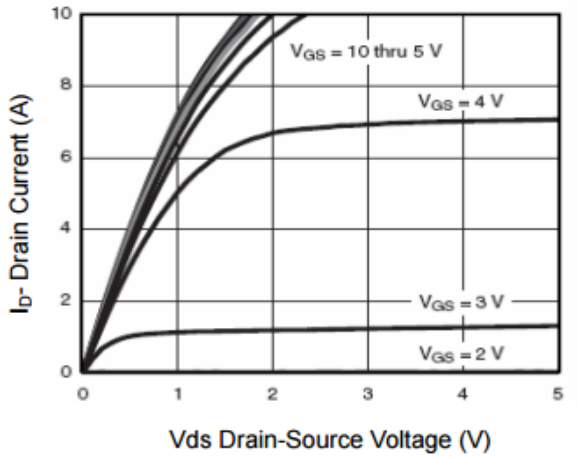


Figure 5 Output Characteristics

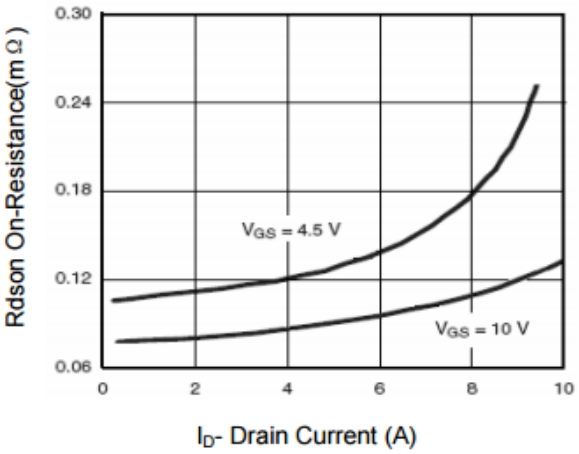


Figure 6 Drain-Source On-Resistance

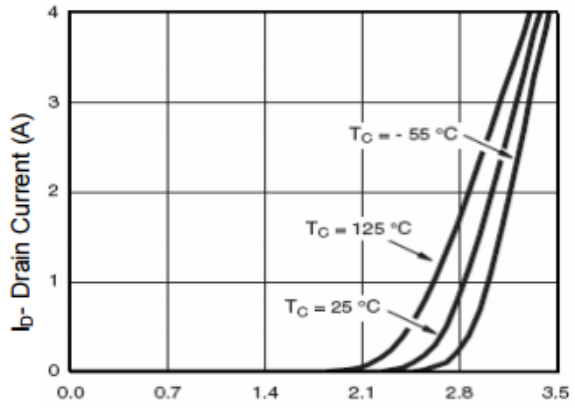


Figure 7 Transfer Characteristics

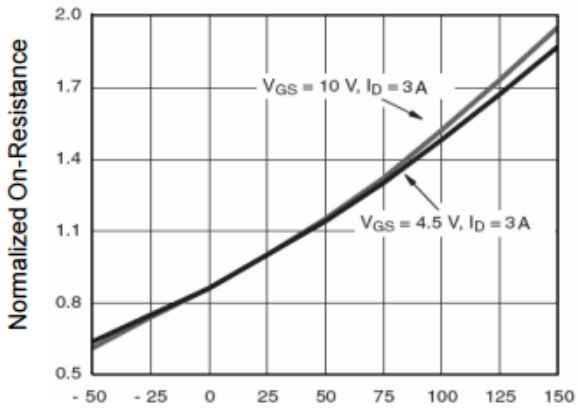


Figure 8 Drain-Source On-Resistance

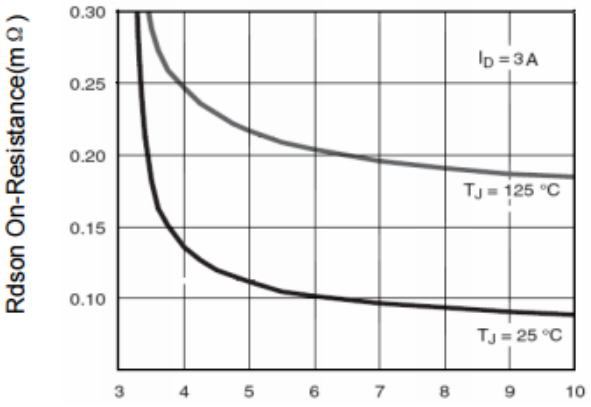


Figure 9 Rdson vs Vgs

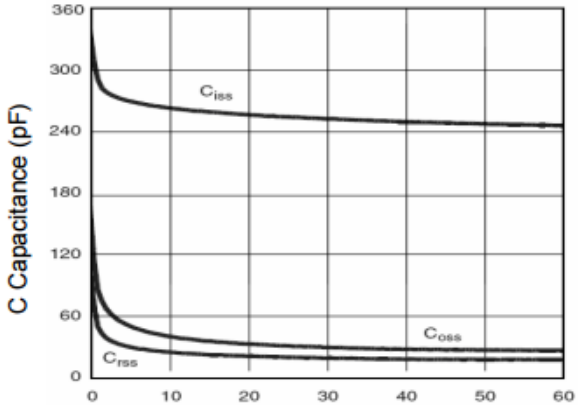


Figure 10 Capacitance vs Vds

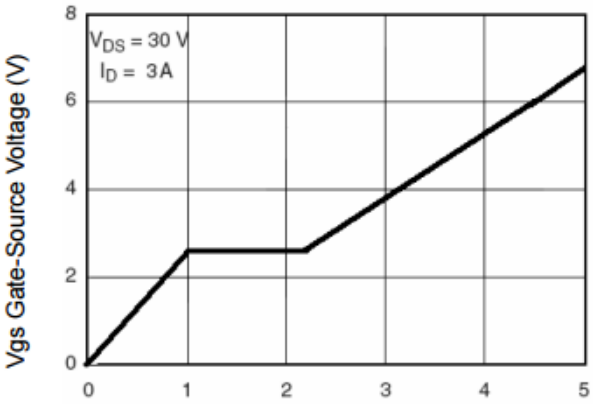


Figure 11 Gate Charge

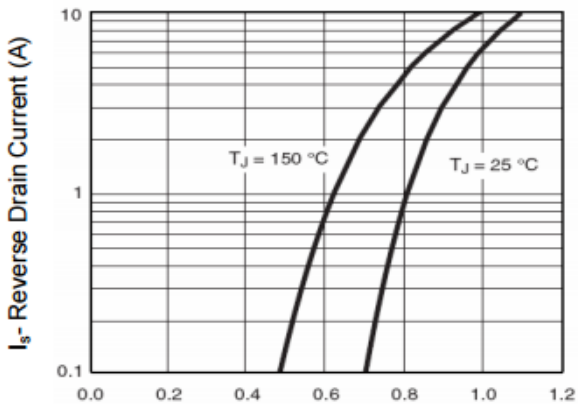


Figure 12 Source- Drain Diode Forward

Company: Wuxi Guang Lei electronic technology co., LTD

TEL: 13961734102 Mr.yuan